

# INTERPACK 2022 PROGRAM-AT-A-GLANCE

Time	Type	Speakers/Tech Sessions	Presentation Title	Company	Room/ Tech Sessions	
<b>Day 1 - Monday, October 24</b>						
7:00 PM	9:30 PM	InterPACK Leadership Dinner - By Invitation Only				
3:00 PM	6:00 PM	Registration Opens				Royal Foyer, First Floor
<b>Day 2 - Tuesday, October 25</b>						
7:30 AM	8:30 AM	Plenary 1	Thomas Kazior	Heterogeneous Integration (HI): An Enabler for Next Generation Systems	DARPA	
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
					Granada Room, Second Floor	
8:30 AM	10:00 AM	Tech Sessions	01-01	02-01	03-01	
8:30 AM	10:00 AM	Panel 1	Women in Engineering			Terrace D-F, First Floor
8:30 AM	10:00 AM	Tutorial 4	Recipe for Heterogenous Integration Packaging Roadmapping			Seville Room, Second Floor
10:00 AM	10:15 AM	Break	Coffee Break / Exhibitor Corner			Royal Foyer, First Floor
10:15 AM	11:45 AM	Workshop 1	Roadmapping Advanced Packaging for Electronics Manufacturing, with INEMI			Royal A & B, First Floor
			Valencia Room, Second Floor	Madrid Room, Second Floor	Granada Room, Second Floor	
10:15 AM	11:45 AM	Tech Sessions	02-02	06-01	08-04	
11:45 AM	1:15 AM	Lunch	Avram Bar Cohen Award Luncheon			Royal C & D, First Floor
1:15 PM	2:15 PM	Plenary 2	Ivor Barber	Integration Strategies in the Chiplet Era	ARPA-E	
2:15 PM	3:45 PM	Workshop 2	MAPT: Microelectronic and Advanced Packaging Technologies Roadmap			Royal A & B, First Floor
2:15 PM	2:45 PM	Track Keynote	Track 5 Form and Function in Power Electronics: Driving Progress in Efficient Energy Conversion by Matched Technology-Topology Integrated Design - Alberto Castellazzi			Regal Room, First Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
					Granada Room, Second Floor	
2:15 PM	3:45 PM	Tech Sessions	05-01	02-03	07-01	
3:45 PM	4:00 PM	Break	Coffee Break / Exhibitor Corner			Royal Foyer, First Floor
4:00 PM	5:30 PM	Panel 8	Heterogeneous Integration Roadmapping			Royal A & B, First Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
4:00 PM	5:30 PM	Tech Sessions	05-02	02-04	06-03	
5:30 PM	7:00 PM	Sponsors	Sponsor Presentations - Raytheon, Jim Wilson, META, Saket Karajigkar, NREL, Sreekant Narumanchi, Intel, Ravi Mahajan			Royal E & F, First Floor
5:30 PM	7:00 PM	Posters	10-01 - Interactive Presentations Session (Posters)			Royal E & F, First Floor
InterPACK Organization Meetings						
7:00 PM	8:00 PM	K-16 Committee Meeting				Seville Room, Second Floor
8:00 PM	9:00 PM	EPPD Meeting				Valencia, Second Floor
<b>Day 3 - Wednesday, October 26</b>						
7:30 AM	8:30 AM	Plenary 3	Mark Spector	Thermal Challenges for Future Military Platforms	Office of Naval Research	
8:30 AM	10:00 AM	Panel 3	Hybrid and System Level Integration for Electronics Packaging			Imperial Room, First Floor
8:30 AM	10:00 AM	Track Keynotes	Track 2: Managing Data Center Challenges in the Age of AI Track 4: High Brightness Illumination Based on Laser Light Diffusion With Mie Scattering Track 8: Patrick McCluskey: Past and Future of Reliability Assessment of Electronic Materials			Regal Room, First Floor
8:30 AM	10:00 AM	Tutorial 2	Advanced Liquid-cooling Technology for ICT: Performance and Economic Benefit			Seville Room, Second Floor
10:00 AM	10:15 AM	Break	Coffee Break / Exhibitor Corner			Royal Foyer, First Floor
10:15 AM	11:45 AM	Panel 4	Pathfinding to Maximize System Performance			Imperial Room, First Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
					Granada Room, Second Floor	
10:15 AM	11:45 AM	Tech Sessions	05-03	02-05	06-04	
10:15 AM	11:45 AM	Tutorial 1	Nanophotonic Systems: Novel Nanophotonics Device and Future Applications in Electronics			Seville Room, Second Floor
11:45 AM	1:15 PM	Lunch	Allan Kraus Awards Luncheon			Royal C & D, First Floor
1:15 PM	2:15 PM	Plenary 4	Philseok Kim	Pushing the Boundaries of Thermal Packaging for Enhanced Performance and Energy Efficiency	ARPA-E	
2:15 PM	3:45 PM	Panel 5	Thermal and Mechanical Challenges and Opportunities of Advanced Mobile/Telecom/IoT/Auto/Computing Devices			Imperial Room, First Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
					Granada Room, Second Floor	
2:15 PM	3:45 PM	Tech Sessions	01-02	04-01	03-02	
2:15 PM	3:45 PM	Workshop 3	Introduction to Robotics, AI, and Intel's OpenVINO Toolkit			Terrace D-F, First Floor
3:45 PM	4:00 PM	Break	Coffee Break / Exhibitor Corner			Royal Foyer, First Floor
4:00 PM	5:30 PM	Panel 6	Sustainable Energy Systems in ICT			Imperial Room, First Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
					Granada Room, Second Floor	
4:00 PM	5:30 PM	Tech Sessions	03-03	02-06	06-05	
4:00 PM	5:30 PM	Workshop 4	K16 Professional Development & Mentoring Workshop			Seville Room, Second Floor
InterPACK Organization Meetings						
5:30 PM	7:00 PM	InterPACK Meeting (Open)				Madrid Room, Second Floor
8:00 PM	8:30 PM	InterPACK Advisory Meeting				Seville, Second Floor
8:30 PM	9:00 PM	Journal of Electronic Packaging (JEP) Meeting				Valencia, Second Floor
<b>Day 4 - Thursday, October 27</b>						
7:30 AM	8:30 AM	Plenary 5	Abhinav Saxena	Use of AI and ML in Improving Industrial Reliability towards Achieving Operational Autonomy – Successes and Challenges	GE Research	
8:30 AM	10:00 AM	Track Keynotes	Track 1: Wining Road to Maximize System Performance Track 3: Anisotropic Conductive Epoxy for High-Volume Manufacturing of Flexible - Stretchable Wearable Electronics Track 9: Building Explainable AI for the Enterprise			Regal Room, First Floor

8:30 AM	10:00 AM	Panel 7	Reliability of Additively Manufactured Electronics			Imperial Room, First Floor
8:30 AM	10:00 AM	Tutorial 3	Optimization of Battery Recycling for Sustainability			Seville Room, Second Floor
10:00 AM	10:15 AM	Break	Coffee Break / Exhibitor Corner			Royal Foyer, First Floor
10:15 AM	11:45 AM	Panel 2	Impact of Sustainability Goals on Future Hardware and Data Center			Imperial Room, First Floor
10:15 AM	11:45 AM	Panel 9	Why AI/Data Science Projects Fail			Seville Room, Second Floor
			Regal Room, First Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	
10:15 AM	11:45 AM	Tech Sessions	05-04	06-06	03-04	
11:45 AM	1:15 PM	Lunch	InterPACK & Nasser Grayeli Poster, EPPD, Intel, JEP, and Best Poster Awards Luncheon			Royal C & D, First Floor
1:15 PM	2:15 PM	Plenary 6	John Williams	Multilayer Flexible Electronic Devices for IoT and RF Applications	Boeing	Royal A & B, First Floor
			Regal Room, Second Floor	Valencia Room, Second Floor	Madrid Room, Second Floor	Granada Room, Second Floor
2:15 PM	3:45 PM	Tech Sessions	09-01	02-07	03-05	08-07
4:00 PM	Conference Ends					